

# DBA

## Jet valve, conductive and non-conductive adhesives

### 1. Product description

DBA (Die Bonding Adhesive) and UFA (Underfill Adhesive) are an adhesive to bond parts on to circuit.



### 2. Benefits

Strong adhesion.

### 3. Processing

DBA and UFA are optimized for dispensing and jet valve process.

### 4. Cleaner

Alcohols, Ketones

### 5. Curing Condition

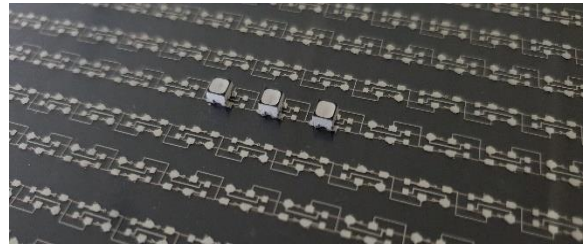
Curing at 115°C for 30 minutes..

### 6. Storage and shelf life

The paste must be well sealed tightly and stored in a refrigerator of 0 to 10 °C (for ACP-002) and frozen of -20 °C (for ACP-001). Unopened paste is valid for three months from the manufacturing date. Exhaust used paste as soon as possible, but mixing used and new products is strictly prohibited.

### 7. Safety and handling

Refer to MSDS for safety and handling information. Leave pastes removed from refrigerator at room temperature for 2 to 3



hours before use. Please exhaust of open products within 7 days.

### 8. Properties

Items	DBA-001	UFA-001
Filler	Silver	Alumina
Binder Type	Epoxy	Epoxy
Color	Grey	Ivory
Viscosity @ 22°C	25,000 ~ 30,000	10,000 ~ 15,000
Thixotropic Index	1.5 ~ 2.0	3.0 ~ 4.0
Curing Conditions	120 °C, 20min	120 °C, 20min
Shelf Life @ -20°C, Months	3 month	3 month
Adhesion force	70.0 ~ 80.0 N	80.0 ~ 90.0 N
Sheet Resistance	3.00 x 10 <sup>12</sup> mΩ/□	10 <sup>12</sup> mΩ/□

### 9. Contact

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